2108AB-2

Properties

Epoxy Resin 2108AB-2 is an epoxy resin that cures under ambient and low-temperature conditions. It features low exothermic reaction, good flowability, natural degassing, high hardness, and can cure at room temperature or with heating.

Applications

Epoxy Resin 2108AB-2 is specifically designed for encapsulation of electronic components, LED strip modules, and other electronic parts. It provides insulation, moisture-proof potting, and confidentiality sealing.

Technical Specifications

Base Resin 2108A-2	Curing Agent 2108B-2	
Color	Colorless and transparent	Colorless and transparent
Density (g/m^3)	1.12 ± 0.05	0.97 ± 0.03
Viscosity (mPa·s)	1200–2500 cps	200–500 cps
Test Method	Brookfield DV2TRV	Brookfield DV2TRV
Mixing Ratio	100:50 (by weight)	
	2:1 (by volume)	

After Mixing

Base Resin + Curing Agent	
State	Liquid
Viscosity	2500 ± 50 mPa·s
Test Method	Brookfield DV2TRV at 25°C

Working Time

100g, 25°C	40 ± 3 minutes
Maximum Viscosity	2500 mPa·s (Brookfield DV2TRV test method)

Usage

| **Application Rate** | 280–350 g/m^2 (varies by substrate) |

Curing Time

Initial Cure	Approximately 10 hours at room temperature
Final Cure	12 hours at room temperature
Operating Temperature Range	10°C–70°C

Usage Instructions

- Ensure the mixing container is clean.
- Strictly follow the weight ratio for mixing components A and B.
- Accurately weigh and thoroughly stir clockwise along the container wall.
- Allow to stand for 3–5 minutes before use.

Precautions

- Mix only the required amount based on working time and usage to avoid waste.
- When the temperature is below 15°C, preheat component A to 30°C before mixing for easier handling (component A thickens at low temperatures).
- Seal the container immediately after use to prevent moisture absorption, which may cause product spoilage.
- When relative humidity exceeds 85%, the cured surface may absorb moisture from the air, forming a white haze. Avoid ambient curing under high humidity; heating curing is recommended.

Test Results

Hardness	Shore D	82
Flexural Strength	kg/mm^2	23
Heat Deflection Temperature	°C	80
Water Absorption	%	<0.15
Compressive Strength	kg/mm^2	8.4

Storage

- **Freeze-Sensitive**: Yes
- **Moisture-Sensitive**: Resin – Not sensitive; Curing Agent – Not sensitive
- **Recommended Storage Temperature**: 15°C–25°C (not below 10°C, not above 50°C)
- **Shelf Life**: 12 months in original packaging
- **Packaging**: 5 kg/pail (resin and curing agent)